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Cautions

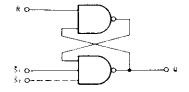
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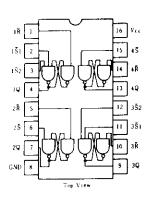
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■ BLOCK DIAGRAM(1/4)



■ PIN ARRANGEMENT



FUNCTION TABLE

Inpu	Outputs	
Š••	R	Q
Н	Н	Q ₀
L	H	Н
Н	1.	I.
L	L	Н*

Notes) 1. H; high level, L; low level

- 2. Qo; The level of Q before the indidicated input conditions were established.
- 3. *; This output level is psodo stable; that is, it may not persist when \overline{S} and \overline{R} inputs return to their inactive (high) level.
- 4. **; For latches with double \$\overline{S}\$ inputs: H; both \$\overline{S}\$ inputs high, L; one or both S inputs low.

ELECTRICAL CHARACTERISTICS ($Ta = -20 \sim +75\%$)

Item	Symbol	Test Conditions		min	typ*	max	Unit
	V_{IH}			2.0	_	_	V
Input voltage	v_{ii}		•	<u> </u>	_	0.8	V
Output voltage	$V_{\scriptscriptstyle GH}$	$V_{ij} = 4.75 \text{ V}, \ V_{iii} = 2 \text{ V}, \ V_{iij} = 0.8 \text{ V}, \ I_{0ii} = -400 \mu\text{A}$				_	V
	V_{ii}	$V_{i'j} = 4.75 \text{V}, \ V_{iji} = 2 \text{V}, \ V_{ij} = 0.8 \text{V}$	Iot = 4 mA	_	_	0.4	V
	Vin	$v_R = 4.75$ $v_R = 2$ $v_R = 0.8$ $v_R = 0.8$	$I_{0i} = 8 \mathrm{mA}$	_	_	0.5	
Input current	In	$V_{ij} = 5.25 \text{V}, V_i = 2.7 \text{V}$		_		20	μA
	In.	$V_{CC} = 5.25 \text{ V}, V_{I} = 0.4 \text{ V}$		_	_	-0.6	mA
	- Iı	$V_{\rm CC} = 5.25 \mathrm{V}, \ V_{\rm f} = 7 \mathrm{V}$		_		0.1	mΑ
Short-circuit output current	Los	$V_{\rm CC} = 5.25 \mathrm{V}$		-20		-100	mA
Supply current**	1cc	$V_{\rm ev} = 5.25 \mathrm{V}$. —	3.8	7	mΑ
Input clamp voltage	V_{IA}	$V_{\rm CC} = 4.75 \text{V}, I_{/N} = -18 \text{ mA}$		-	_	. 1.5	V

^{*} VCC=5V. Ta=25°C

ESWITCHING CHARACTERISTICS ($V_{cc} = 5V$, Ta = 25%)

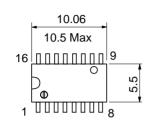
Item	Symbol	Inputs	Output	Test Conditions	min	typ	max	Unit
Propagation delay time	t ₽LH	ē		$C_L = 15 \mathrm{pF},$ $R_L = 2 \mathrm{k}\Omega$		12	22	ns
	I PHI.	7 5	Q			13	21	ns
	t _{PHL}	R				15	27	ns

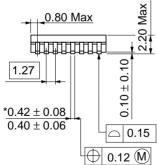
Note) Refer to Test Circuit and Waveform of the Common Item

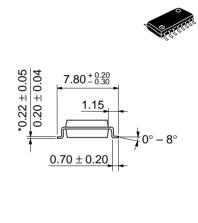
^{**} I_{CC} is measured with all \overline{R} inputs grounded, all \overline{S} inputs at 4.5V, and all outputs open.

Unit: mm 19.20 20.00 Max 16 7.40 Max 6.30 1.3 1.11 Max 7.62 5.06 Max 2.54 Min 0.51 Min $0.25^{+0.13}_{-0.05}$ 0.48 ± 0.10 2.54 ± 0.25 $0^{\circ} - 15^{\circ}$ Hitachi Code DP-16 **JEDEC** Conforms EIAJ Conforms Weight (reference value) 1.07 g

Unit: mm

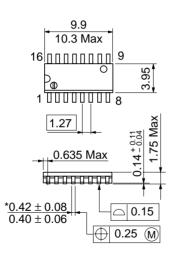


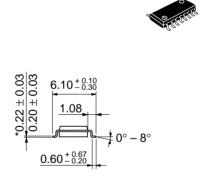




	Hitachi Code	FP-16DA
	JEDEC	_
Dimension including the plating thickness	EIAJ	Conforms
Base material dimension	Weight (reference value)	0.24 a

Unit: mm





Hitachi Code

*Dimension including the plating thickness
Base material dimension

Tillacili Code	TT-TODIN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.15 g

FD-16DN

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